

**A PA-CVD PROCESS FOR DEPOSITION OF A SOLID METAL-CONTAINING FILM ONTO A SUBSTRATE CONTAINING AT LEAST 50 % of Fe or WC**

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Patent Number: WO9618756  
Publication date: 1996-06-20  
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Requested Patent: ☐ WO9618756  
Application Number: WO1995DK00505 19951215  
Priority Number(s): DK19940001436 19941216  
IPC Classification: C23C16/08; C23C16/30; C23C16/50  
EC Classification: C23C16/08, C23C16/32, C23C16/34  
EC Classification: C23C16/08; C23C16/32; C23C16/34  
Equivalents:

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**Abstract**

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A new plasma assisted chemical vapour deposition (PA-CVD) process for deposition of a solid metal-containing film onto the surface of a substrate containing at least 50 % of Fe or WC (such as hard metal or steel), by which the metallic component of the metal-containing film is introduced into the system as a metal halide, is disclosed. The new process involves shifting the process gas composition between a high and a low metal halide level, whereby the adhesion of the deposited film to the substrate is improved.